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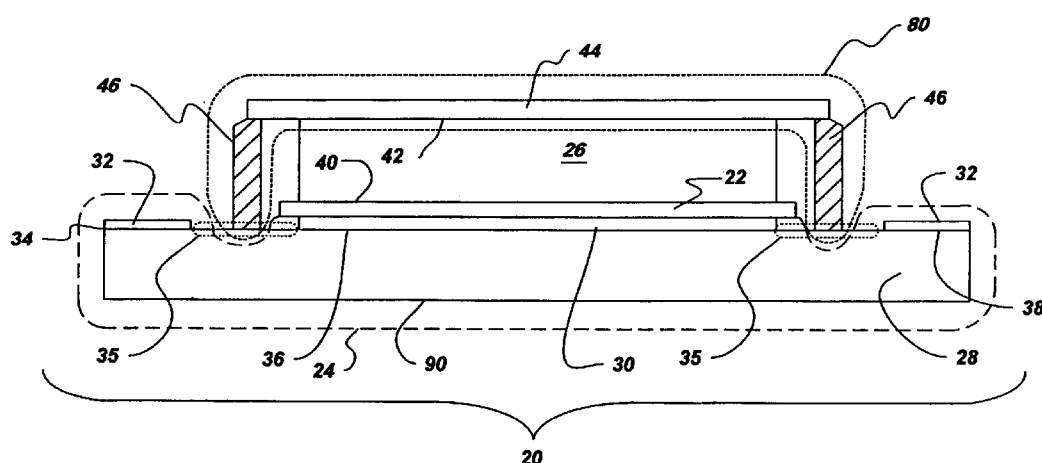
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(54) Title: SYSTEMS AND METHODS FOR DETECTING IONIZING RADIATION WITH AN IMAGING SYSTEM



(57) Abstract: A radiation imaging system (20) comprising a scintillator (26), an imager array (30), and a lamination layer (22). Lamination layer (22) bonds and optically couples scintillator (26) to imager array (30). Lamination layer (22) is comprised of a lamination material that is substantially free from void spaces. Radiation imaging system (20) fabrication comprises the steps of disposing lamination layer (22) between a light imager (24) and a scintillator (26) to form a subassembly (150). Light imager (24) comprises imager array (30), an imaging plate surface (34) and a plurality of contact pads (32). Additional steps include subjecting subassembly (150) to a vacuum; heating subassembly (150) to a bonding temperature, exerting a bonding force on subassembly (150), maintaining the vacuum, the bonding temperature and the bonding force until light imager (24) is bonded to the scintillator (26) and the lamination layer (22) is comprised of lamination material that is substantially free from void spaces.



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